

**MBR5H150** 

### **General Description**

High voltage schottky rectifier suited for switch mode power supplies and other power converters. This device is intended for use in medium voltage operation, and particularly, in high frequency circuits where low switching losses and low noise are required.

The MBR5H150 is available in standard DO-27 and DO-27(A) packages.

### **Main Product Characteristics**

I <sub>F(AV)</sub>	5A		
$V_{RRM}$	150V		
T <sub>J</sub>	175°C		
$V_{F(max)}$	0.92V		

#### **Features**

- High Surge Capacity
- Low Forward Voltage Drop
- 175°C Operating Junction Temperature
- Guard-Ring for Stress Protection
- Pb-Free and Halogen-Free Packages are available
- The Plastic Material Carries UL Recongnition 94V-0

### **Mechanical Characteristics**

- Case: JEDEC DO-201AD Molded Plastic
- Epoxy Meets UL 94 V-0@ 0.125 in
- Weight (Approximately): 1.2 Grams
- Finish: All External Surfaces Corrosion Resistant and Terminal

### **Applications**

- Power Supply Output Rectification
- Power Management
- Instrumentation

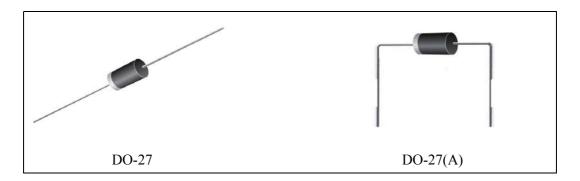


Figure 1. Package Type of MBR5H150



**MBR5H150** 

### **Pin Configuration**

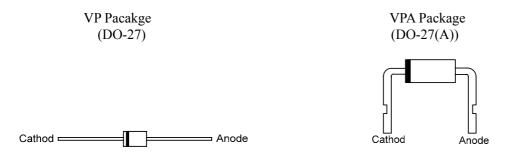
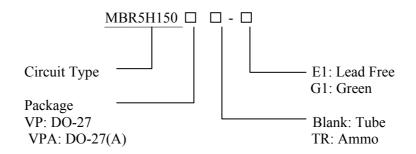


Figure 2. Pin Configuration of MBR5H150 (Top View)

## **Ordering Information**



Doolzago	Part N	Marking ID		Packing		
Package	Lead Free	Green	Lead Free	Green	Type	
DO 27	MBR5H150VP-E1	MBR5H150VP-G1	515VP	515VPG	Bulk	
DO-27	MBR5H150VPTR-E1	MBR5H150VPTR-G1	515VP	515VPG	Ammo	
DO-27(A)	MBR5H150VPA-E1	MBR5H150VPA-G1	515VP	515VPG	Bulk	

BCD Semiconductor's Pb-free products, as designated with "E1" suffix in the part number, are RoHS compliant. Products with "G1" suffix are available in green packages.



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## Absolute Maximum Ratings (Per Diode Leg) (Note 1)

Parameter	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$		
Working Peak Reverse Voltage	$V_{RWM}$	150	V
DC Blocking Voltage	$V_R$		
Average Rectified Forward Current	Incorn	5	Α
(Rated $V_R$ ) $T_C = 150$ °C	$I_{F(AV)}$	3	А
Non repetitive Peak Surge Current	$I_{FSM}$	125	A
(Surge applied at rated load conditions half wave, single phase, 60Hz)	1FSM	123	71
Operating Junction Temperature Range (Note 2)	$T_{J}$	175	°C
Storage Temperature Range	$T_{STG}$	-55 to 175	°C
Voltage Rate of Change (Rated V <sub>R</sub> )	dv/dt	10000	V/µs
ESD Ratings: Machine Model = C		> 400	V
Human Body Model =3B		> 8000	V

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Note 2: The heat generated must be less than the thermal conductivity from Junction–to–Ambient:  $dP_D/dT_J < 1/\theta_{JA}$ .

## **Recommended Operating Conditions**

Parameter	Symbol	Condition	Value	Unit
Maximum Thermal Resistance	$\theta_{JC}$	Junction to Case	TBD	
	$\theta_{\mathrm{JA}}$	Junction to Ambient	TBD	°C/W

#### **Electrical Characteristics**

Parameter	Symbol	Conditions	Value	Units
Maximum Instantaneous Forward Voltage Drop (Note 3)	$V_{\mathrm{F}}$	I <sub>F</sub> =5A, T <sub>C</sub> =25°C	0.92	V
Maximum Instantaneous Reverse Current (Note 3)	$I_R$	Rated DC Voltage, $T_C=25$ °C	8.0	μΑ
		Rated DC Voltage, $T_C=150$ °C	50.0	mA

Note 3: Pulse Test: Pulse Width =  $300\mu s$ , Duty Cycle  $\leq 2.0\%$ .



## **MBR5H150**

## **Typical Performance Characteristics**

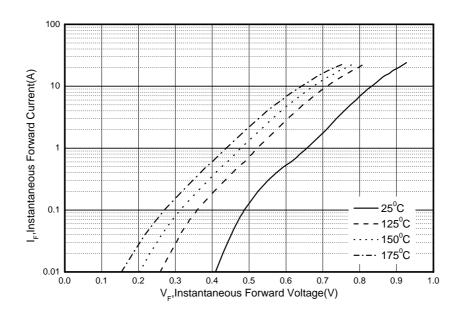


Figure 3. Typical Forward Characteristics

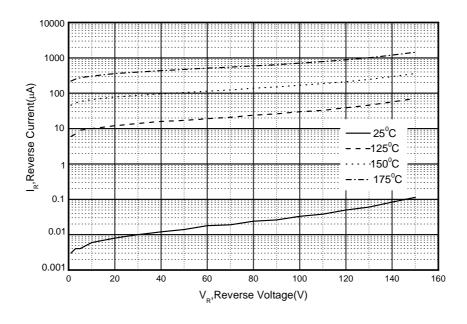


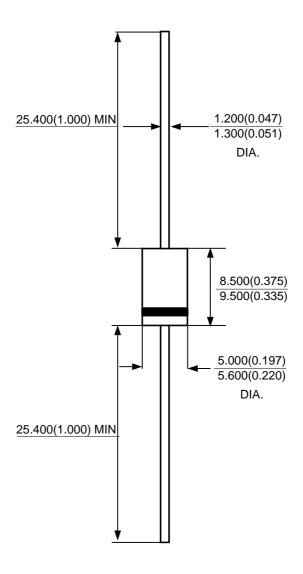
Figure 4. Typical Reverse Characteristics



**MBR5H150** 

## **Mechanical Dimensions**

DO-27 Unit: mm(inch)

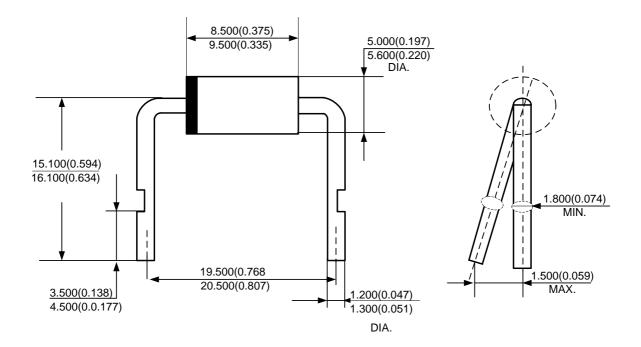




**MBR5H150** 

## **Mechanical Dimensions (Continued)**

DO-27(A) Unit: mm(inch)







### **BCD Semiconductor Manufacturing Limited**

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